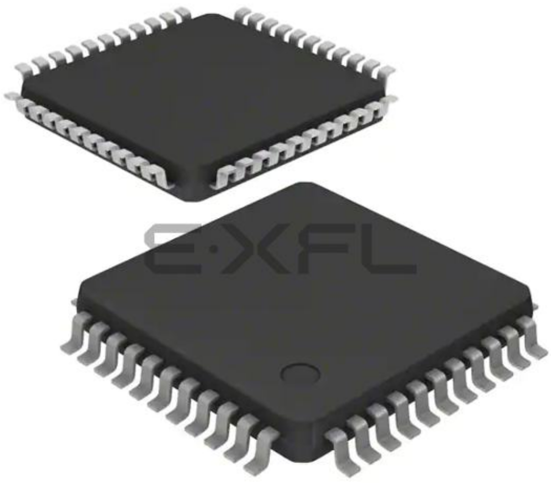

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	Z8
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	4KB (4K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	236 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86e4016aeg

PIN IDENTIFICATION (Continued)

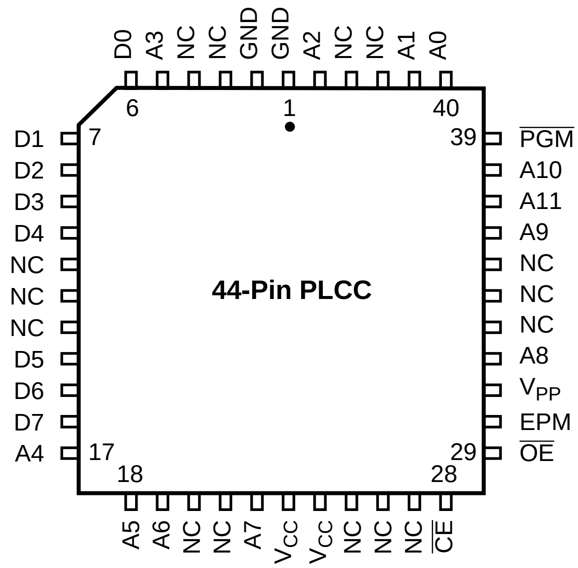


Figure 7. 44-Pin PLCC Pin Configuration EPROM Programming Mode

Table 5. 44-Pin PLCC Pin Configuration EPROM Programming Mode

Pin #	Symbol	Function	Direction
1–2	GND	Ground	
3–4	NC	No Connection	
5	A3	Address 3	Input
6–10	D0–D4	Data 0,1,2,3,4	In/Output
11–13	NC	No Connection	
14–16	D5–D7	Data 5,6,7	In/Output
17–19	A4–A6	Address 4,5,6	Input
20–21	NC	No Connection	
22	A7	Address 7	Input
23–24	V_{CC}	Power Supply	
25–27	NC	No Connection	
28	$\overline{CE}$	Chip Select	Input
29	$\overline{OE}$	Output Enable	Input
30	EPM	EPROM Prog. Mode	Input
31	V_{PP}	Prog. Voltage	Input
32	A8	Address 8	Input
33–35	NC	No Connection	
36	A9	Address 9	Input
37	A11	Address 11	Input
38	A10	Address 10	Input
39	$\overline{PGM}$	Prog. Mode	Input
40–41	A0,A1	Address 0,1	Input
42–43	NC	No Connection	
44	A2	Address 2	Input

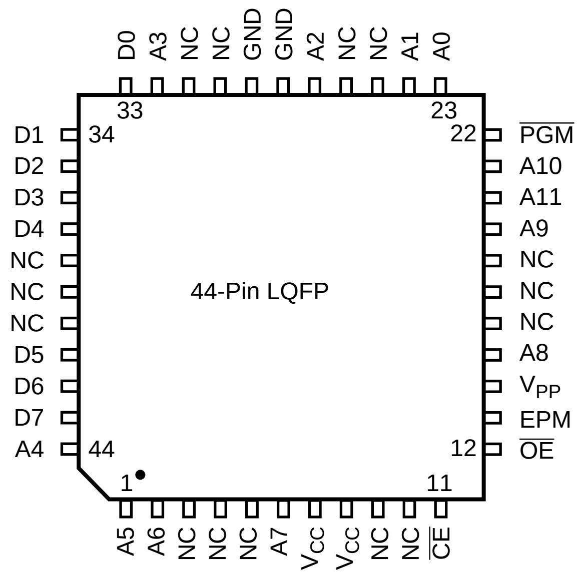


**Figure 8. 44-Pin LQFP Pin Configuration
EPROM Programming Mode**

**Table 6. 44-Pin LQFP Pin Configuration
EPROM Programming Mode**

Pin #	Symbol	Function	Direction
1–2	A5–A6	Address 5,6	Input
3–4	NC	No Connection	
5	A7	Address 7	Input
6–7	V_{CC}	Power Supply	
8–10	NC	No Connection	
11	$\overline{CE}$	Chip Select	Input
12	$\overline{OE}$	Output Enable	Input
13	EPM	EPROM Prog. Mode	Input
14	V_{PP}	Prog. Voltage	Input
15	A8	Address 8	Input
16–18	NC	No Connection	
19	A9	Address 9	Input
20	A11	Address 11	Input
21	A10	Address 10	Input
22	$\overline{PGM}$	Prog. Mode	Input

**Table 6. 44-Pin LQFP Pin Configuration
EPROM Programming Mode**

Pin #	Symbol	Function	Direction
23–24	A0,A1	Address 0,1	Input
25–26	NC	No Connection	
27	A2	Address 2	Input
28–29	GND	Ground	
30–31	NC	No Connection	
32	A3	Address 3	Input
33–37	D0–D4	Data 0,1,2,3,4	In/Output
38–40	NC	No Connection	
41–43	D5–D7	Data 5,6,7	In/Output
44	A4	Address 4	Input

PIN IDENTIFICATION (Continued)

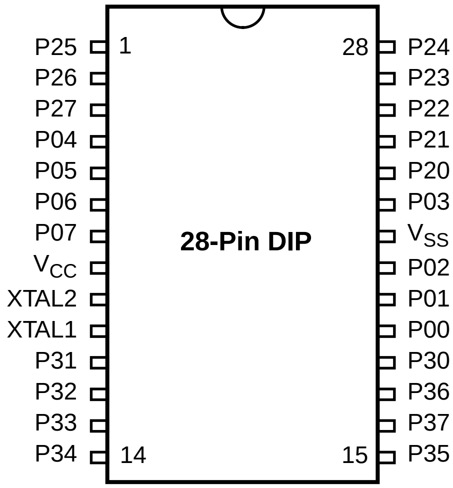


Figure 9. Standard Mode 28-Pin DIP/SOIC Pin Configuration

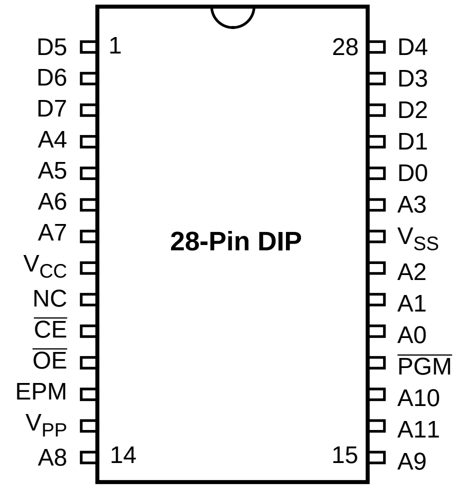


Figure 10. EPROM Programming Mode 28-Pin DIP/SOIC Pin Configuration

Table 7. 28-Pin DIP/SOIC/PLCC Pin Identification*

Pin #	Symbol	Function	Direction
1–3	P25–P27	Port 2, Pins 5,6,	In/Output
4–7	P04–P07	Port 0, Pins 4,5,6,7	In/Output
8	V_{CC}	Power Supply	
9	XTAL2	Crystal Oscillator	Output
10	XTAL1	Crystal Oscillator	Input
11–13	P31–P33	Port 3, Pins 1,2,3	Input
14–15	P34–P35	Port 3, Pins 4,5	Output
16	P37	Port 3, Pin 7	Output
17	P36	Port 3, Pin 6	Output
18	P30	Port 3, Pin 0	Input
19–21	P00–P02	Port 0, Pins 0,1,2	In/Output
22	V_{SS}	Ground	
23	P03	Port 0, Pin 3	In/Output
24–28	P20–P24	Port 2, Pins 0,1,2,3,4	In/Output

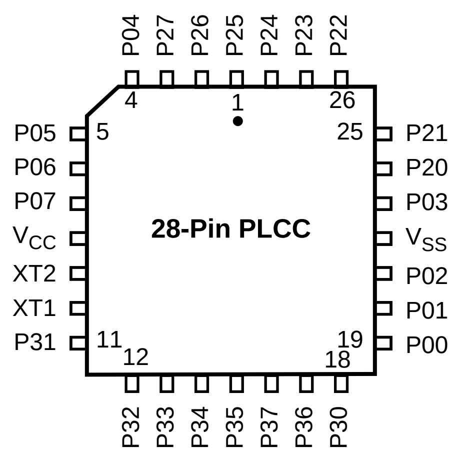


Figure 11. Standard Mode 28-Pin PLCC Pin Configuration

ABSOLUTE MAXIMUM RATINGS

Parameter	Min	Max	Units
Ambient Temperature under Bias	–40	+105	C
Storage Temperature	–65	+150	C
Voltage on any Pin with Respect to V_{SS} [Note 1]	–0.6	+7	V
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V
Voltage on XTAL1 and $\overline{RESET}$ Pins with Respect to V_{SS} [Note 2]	–0.6	V_{DD}+1	V
Total Power Dissipation		1.21	W
Maximum Allowable Current out of V_{SS}		220	mA
Maximum Allowable Current into V_{DD}		180	mA
Maximum Allowable Current into an Input Pin [Note 3]	–600	+600	µA
Maximum Allowable Current into an Open-Drain Pin [Note 4]	–600	+600	µA
Maximum Allowable Output Current Sinked by Any I/O Pin		25	mA
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA
Maximum Allowable Output Current Sinked by $\overline{RESET}$ Pin		3 mA	

Notes:
1. This applies to all pins except XTAL pins and where otherwise noted.
2. There is no input protection diode from pin to V_{DD}.
3. This excludes XTAL pins.
4. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability.

Total power dissipation should not exceed 1.2 W for the package. Power dissipation is calculated as follows:

Total Power Dissipation = V_{DD} x [I_{DD} – (sum of I_{OH})]
+ sum of [(V_{DD} – V_{OH}) x I_{OH}]
+ sum of (V_{0L} x I_{0L})

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Test Load).

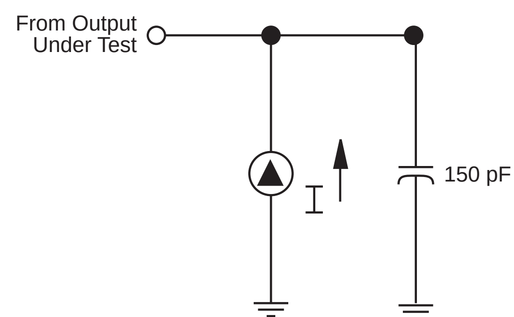


Figure 13. Test Load Diagram

DC ELECTRICAL CHARACTERISTICS (Continued)

			T_A=–40 °C to +105 °C					
Sym	**Parameter**	**V_{CC} Note [3]**	**Min**	**Max**	**Typical @ 25°C**	**Units**	**Conditions**	**Notes**
I_{ALH}	Auto Latch High Current	4.5V	-1.0	-10	-3.8	µA	0V < V_{IN} < V_{CC}	9
		5.5V	-1.0	-10	-3.8	µA	0V < V_{IN} < V_{CC}	9
T_{POR}	Power On Reset	4.5V	2.0	14	4	mS		
		5.5V	2.0	14	4	mS		
V_{LV}	Auto Reset Voltage		2.0	3.3	2.9	V		1

1. Device does function down to the Auto Reset voltage.
2. GND=0V
3. The V_{CC} voltage specification of 5.5V guarantees 5.0V ± 0.5V.
4. All outputs unloaded, I/O pins floating, inputs at rail.
5. CL1= CL2 = 22 pF
6. Same as note [4] except inputs at V_{CC}.
7. Maximum temperature is 70°C
8. STD Mode (not Low EMI Mode)
9. Auto Latch (mask option) selected
10. For analog comparator inputs when analog comparators are enabled.
11. Clock must be forced Low, when XTAL1 is clock driven and XTAL2 is floating.
12. Typicals are at V_{CC} = 5.0V
13. Z86E40 only
14. WDT is not running.

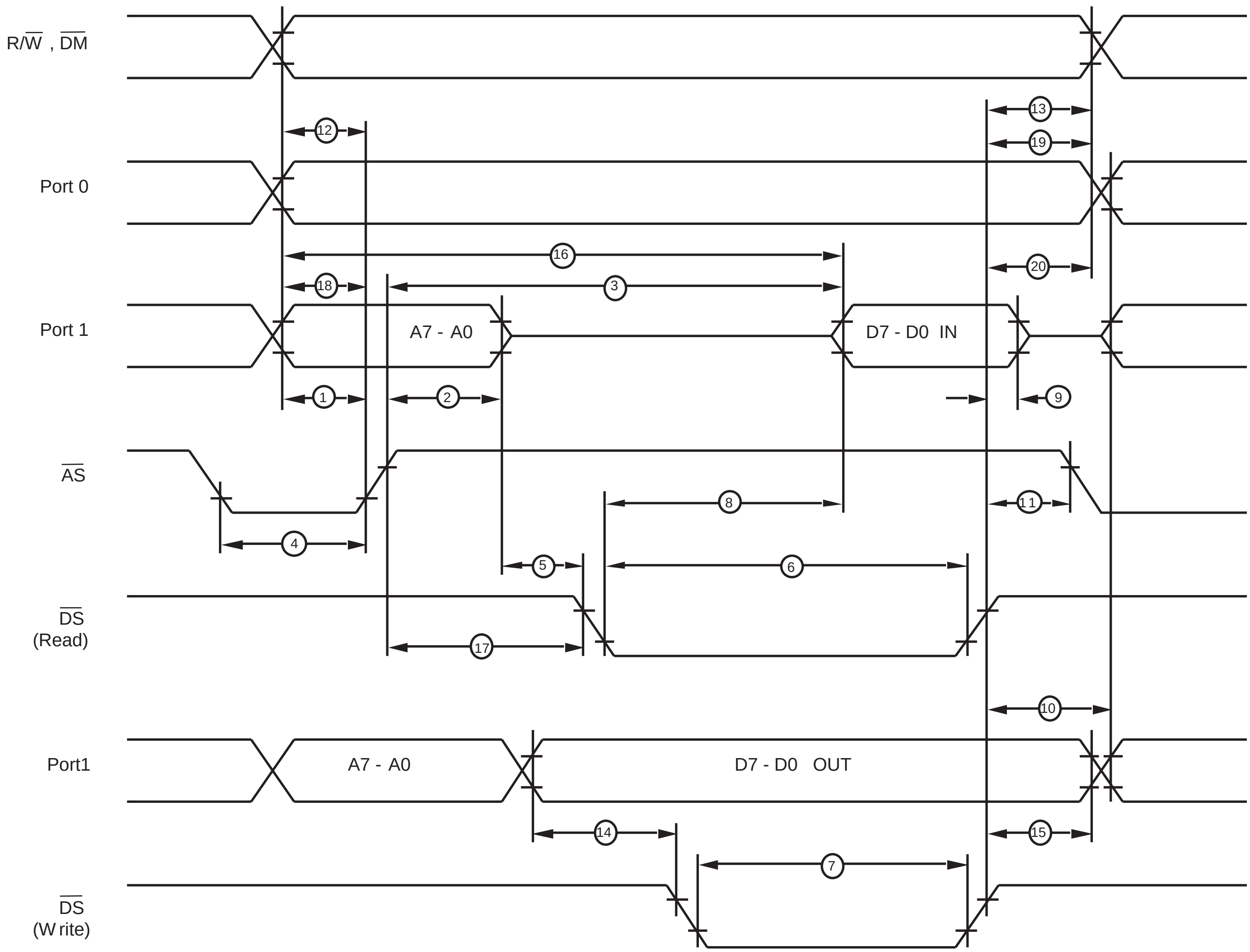


Figure 14. External I/O or Memory Read/Write Timing Z86E40 Only

DC ELECTRICAL CHARACTERISTICS (Continued)

				T_A = 0°C to 70°C 16 MHz			
No	Symbol	Parameter	Note [3] V_{CC}	Min	Max	Units	Notes
1	TdA(AS)	Address Valid to $\overline{AS}$ Rise Delay	3.5V 5.5V	25 25		ns ns	2
2	TdAS(A)	$\overline{AS}$ Rise to Address Float Delay	3.5V 5.5V	35 35		ns ns	2
3	TdAS(DR)	$\overline{AS}$ Rise to Read Data Req'd Valid	3.5V 5.5V		180 180	ns ns	1,2
4	TwAS	$\overline{AS}$ Low Width	3.5V 5.5V	40 40		ns ns	2
5	TdAS(DS)	Address Float to $\overline{DS}$ Fall	3.5V 5.5V	0 0		ns ns	
6	TwDSR	$\overline{DS}$ (Read) Low Width	3.5V 5.5V	135 135		ns ns	1,2
7	TwDSW	$\overline{DS}$ (Write) Low Width	3.5V 5.5V	80 80		ns ns	1,2
8	TdDSR(DR)	$\overline{DS}$ Fall to Read Data Req'd Valid	3.5V 5.5V		75 75	ns ns	1,2
9	ThDR(DS)	Read Data to $\overline{DS}$ Rise Hold Time	3.5V 5.5V	0 0		ns ns	2
10	TdDS(A)	$\overline{DS}$ Rise to Address Active Delay	3.5V 5.5V	50 50		ns ns	2
11	TdDS(AS)	$\overline{DS}$ Rise to $\overline{AS}$ Fall Delay	3.5V 5.5V	35 35		ns ns	2
12	TdR/W(AS)	R/$\overline{W}$ Valid to $\overline{AS}$ Rise Delay	3.5V 5.5V	25 25		ns ns	2
13	TdDS(R/W)	$\overline{DS}$ Rise to R/$\overline{W}$ Not Valid	3.5V 5.5V	35 35		ns ns	2
14	TdDW(DSW)	Write Data Valid to $\overline{DS}$ Fall (Write) Delay	3.5V 5.5V	55 55	25 25	ns ns	2
15	TdDS(DW)	$\overline{DS}$ Rise to Write Data Not Valid Delay	3.5V 5.5V	35 35		ns ns	2
16	TdA(DR)	Address Valid to Read Data Req'd Valid	3.5V 5.5V		230 230	ns ns	1,2
17	TdAS(DS)	$\overline{AS}$ Rise to $\overline{DS}$ Fall Delay	3.5V 5.5V	45 45		ns ns	2
18	TdDM(AS)	$\overline{DM}$ Valid to $\overline{AS}$ Fall Delay	3.5V 5.5V	30 30		ns ns	2
20	ThDS(AS)	$\overline{DS}$ Valid to Address Valid Hold Time	3.5V 5.5V	35 35		ns ns	

Notes:
1. When using extended memory timing, add 2 TpC.
2. Timing numbers given are for minimum TpC.
3. The V_{CC} voltage specification of 5.5V guarantees 5.0V ±0.5V and the V_{CC} voltage specification of 3.5V guarantees only 3.5V

Standard Test Load
All timing references use 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
For Standard Mode (not Low-EMI Mode for outputs) with SMR D1 = 0, D0 = 0.

DC ELECTRICAL CHARACTERISTICS (Continued)

Handshake Timing Diagrams

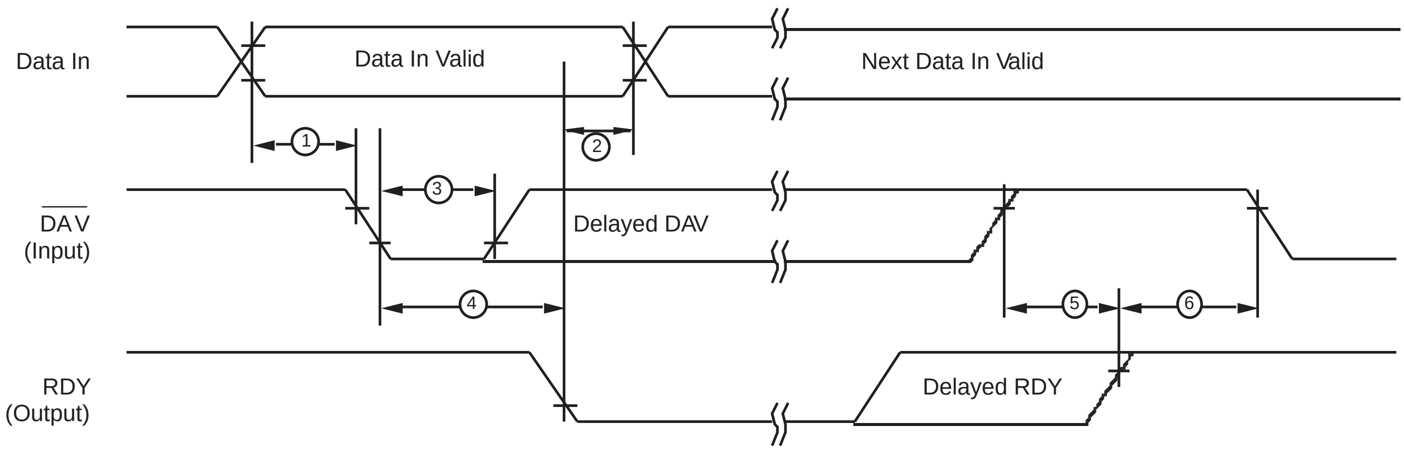


Figure 16. Input Handshake Timing

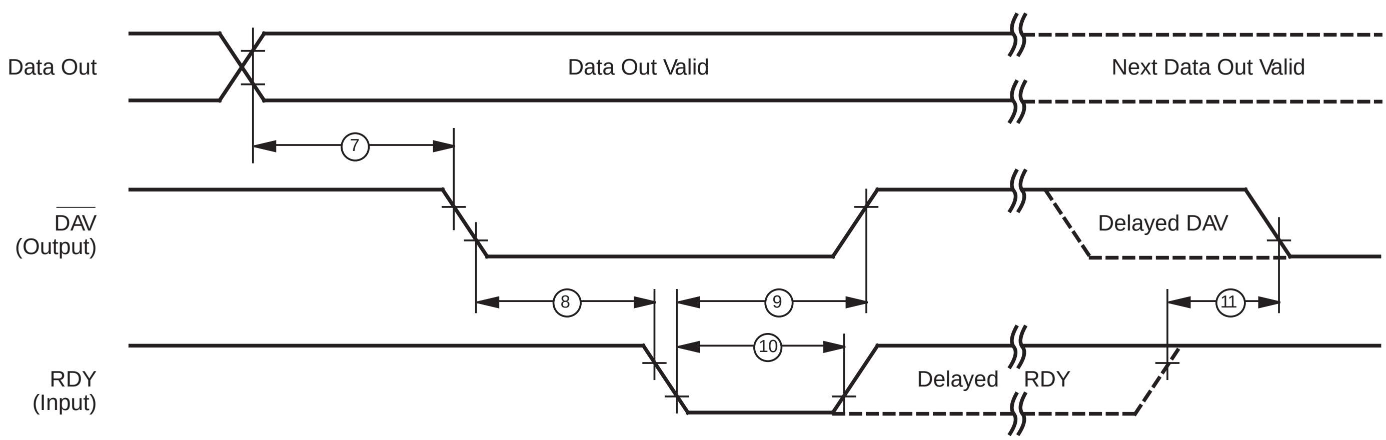


Figure 17. Output Handshake Timing

FUNCTIONAL DESCRIPTION

The MCU incorporates the following special functions to enhance the standard Z8 architecture to provide the user with increased design flexibility.

RESET. The device is reset in one of three ways:

1. Power-On Reset
2. Watch-Dog Timer
3. STOP-Mode Recovery Source

Note: Having the Auto Power-On Reset circuitry built-in, the MCU does not need to be connected to an external power-on reset circuit. The reset time is 5 ms (typical). The MCU does not reinitialize WDTMR, SMR, P2M, and P3M registers to their reset values on a STOP-Mode Recovery operation.

Note: The device V_{CC} must rise up to the operating V_{CC} specification before the TPOR expires.

Program Memory. The MCU can address up to 4 KB of Internal Program Memory (Figure 22). The first 12 bytes of program memory are reserved for the interrupt vectors. These locations contain six 16-bit vectors that correspond to the six available interrupts. For EPROM mode, byte 12 (000CH) to address 4095 (0FFFH) consists of programmable EPROM. After reset, the program counter points at the address 000CH, which is the starting address of the user program.

In ROMless mode, the Z86E40 can address up to 64 KB of External Program Memory. The ROM/ROMless option is only available on the 44-pin devices.

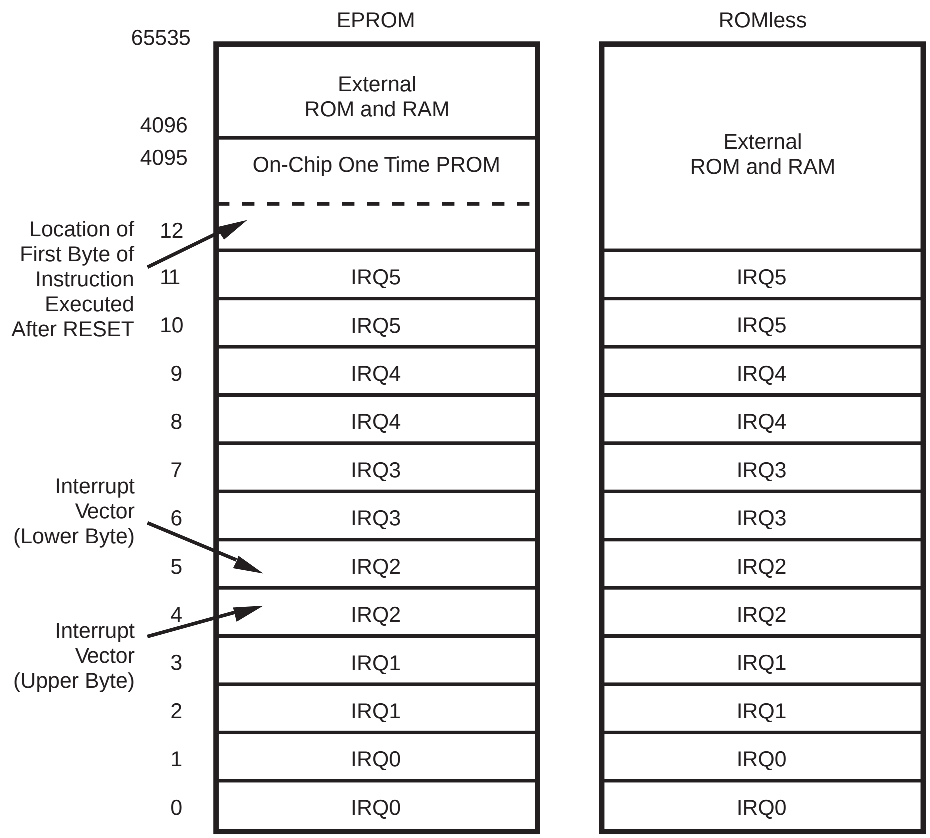


Figure 22. Program Memory Map (ROMless Z86E40 Only)

EPROM Protect. When in ROM Protect Mode, and executing out of External Program Memory, instructions LDC, LDCI, LDE, and LDEI cannot read Internal Program Memory.

When in ROM Protect Mode and executing out of Internal Program Memory, instructions LDC, LDCI, LDE, and LDEI can read Internal Program Memory.

FUNCTIONAL DESCRIPTION (Continued)

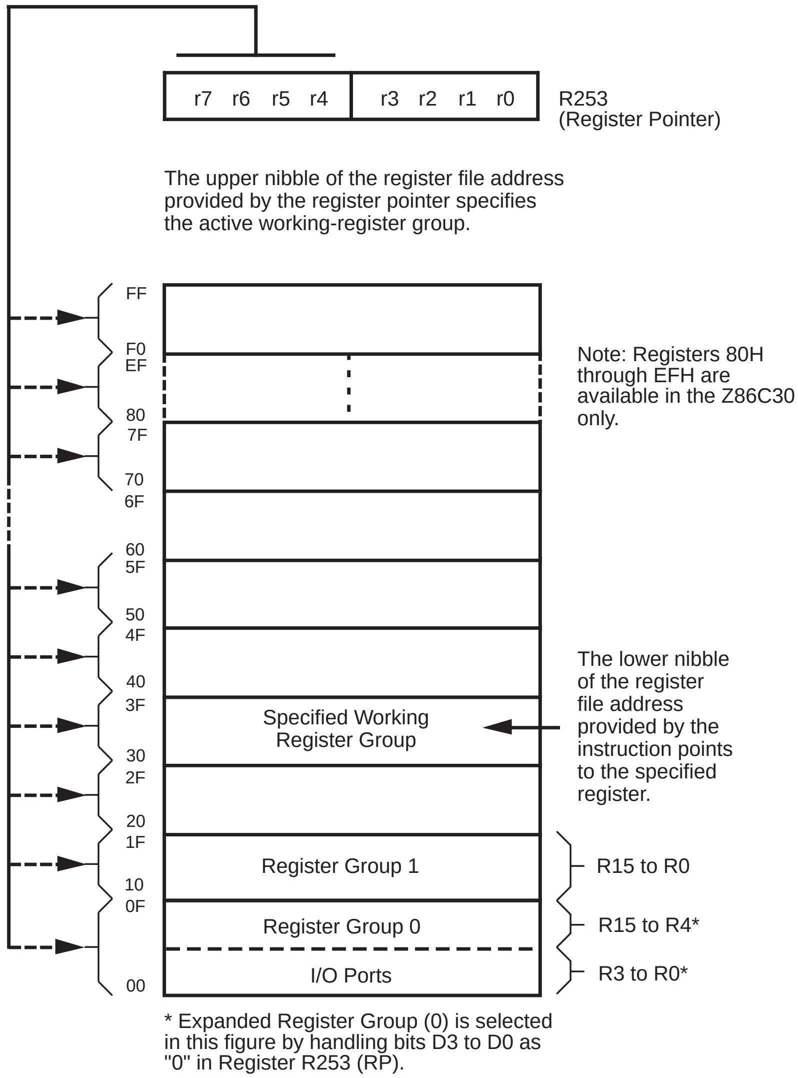


Figure 25. Register Pointer

When more than one interrupt is pending, priorities are resolved by a programmable priority encoder that is controlled by the Interrupt Priority Register (IPR). An interrupt machine cycle is activated when an interrupt request is granted. Thus, disabling all subsequent interrupts, saves the Program Counter and Status Flags, and then branches to the program memory vector location reserved for that interrupt. All interrupts are vectored through locations in the program memory. This memory location and the next byte contain the 16-bit starting address of the interrupt service routine for that particular interrupt request.

To accommodate polled interrupt systems, interrupt inputs are masked and the interrupt request register is polled to determine which of the interrupt requests need service.

An interrupt resulting from AN1 is mapped into IRQ2, and an interrupt from AN2 is mapped into IRQ0. Interrupts IRQ2 and IRQ0 may be rising, falling or both edge triggered, and are programmable by the user. The software may poll to identify the state of the pin.

Programming bits for the Interrupt Edge Select are located in bits D7 and D6 of the IRQ Register (R250). The configuration is shown in Table 11.

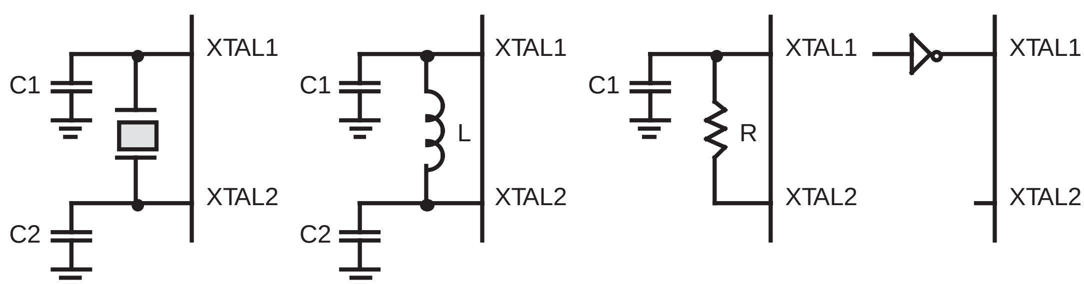
Table 11. IRQ Register Configuration

IRQ		Interrupt Edge	
D7	**D6**	**P31**	**P32**
0	0	F	F
0	1	F	R
1	0	R	F
1	1	R/F	R/F

Notes:
F = Falling Edge
R = Rising Edge

Clock. The on-chip oscillator has a high-gain, parallel-resonant amplifier for connection to a crystal, RC, ceramic resonator, or any suitable external clock source (XTAL1 = Input, XTAL2 = Output). The crystal should be AT cut, 10 KHz to 16 MHz max, with a series resistance (RS) less than or equal to 100 Ohms.

The crystal should be connected across XTAL1 and XTAL2 using the vendor's recommended capacitor values from each pin directly to device pin Ground. The RC oscillator option can be selected in the programming mode. The RC oscillator configuration must be an external resistor connected from XTAL1 to XTAL2, with a frequency-setting capacitor from XTAL1 to Ground (Figure 29).



Ceramic Resonator or Crystal
C1, C2 = 47 pF TYP *
F = 8 MHz

LC
C1, C2 = 22 pF

L = 130 µH *
F = 3 MHz *

RC
@ 5V Vcc (TYP)

C1 = 100 pF
R = 2K
F = 6 MHz

External Clock

* Typical value including pin parasitics

Figure 29. Oscillator Configuration

FUNCTIONAL DESCRIPTION (Continued)

Power-On Reset (POR). A timer circuit clocked by a dedicated on-board RC oscillator is used for the Power-On Reset (POR) timer function. The POR timer allows V_{CC} and the oscillator circuit to stabilize before instruction execution begins.

The POR timer circuit is a one-shot timer triggered by one of three conditions:

1. Power fail to Power OK status
2. Stop-Mode Recovery (if D5 of SMR=0)
3. WDT time-out

The POR time is a nominal 5 ms. Bit 5 of the STOP mode Register (SMR) determines whether the POR timer is bypassed after STOP-Mode Recovery (typical for an external clock and RC/LC oscillators with fast start up times).

HALT. Turns off the internal CPU clock, but not the XTAL oscillation. The counter/timers and external interrupt IRQ0, IRQ1, and IRQ2 remain active. The device is recovered by interrupts, either externally or internally generated. An interrupt request must be executed (enabled) to exit HALT Mode. After the interrupt service routine, the program continues from the instruction after the HALT.

In order to enter STOP or HALT Mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To do this, the user must execute a NOP (Opcode=FFH) immediately before the appropriate sleep instruction, that is:

```
FF    NOP    ; clear the pipeline
6F    STOP   ; enter STOP Mode
       or
FF    NOP    ; clear the pipeline
7F    HALT   ; enter HALT Mode
```

STOP. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 microamperes or less. STOP Mode is terminated by one of the following resets: either by WDT time-out, POR, a Stop-Mode Recovery Source, which is defined by the SMR register or external reset. This causes the processor to restart the application program at address 000CH.

Port Configuration Register (PCON). The PCON register configures the ports individually; comparator output on Port 3, open-drain on Port 0 and Port 1, low EMI on Ports 0, 1, 2 and 3, and low EMI oscillator. The PCON register is located in the expanded register file at Bank F, location 00 (Figure 30).

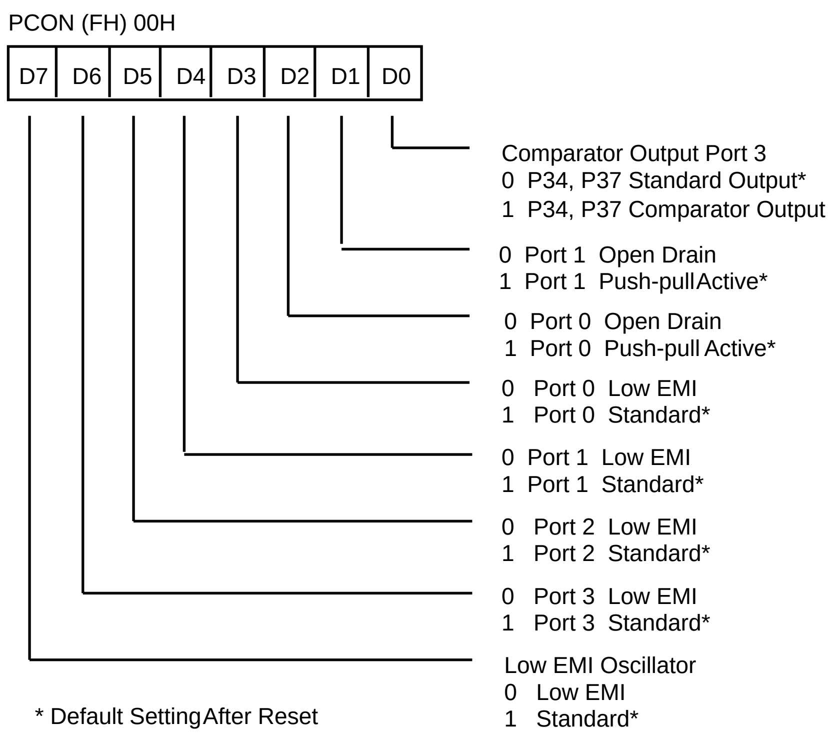


Figure 30. Port Configuration Register (PCON) (Write Only)

cycles from the execution of the first instruction after Power-On Reset, Watch-Dog reset or a STOP-Mode Recovery (Figures 33 and 34). After this point, the register cannot be modified by any means, intentional or otherwise. The WDTMR cannot be read and is located in Bank F of the Expanded Register Group at address location 0FH.

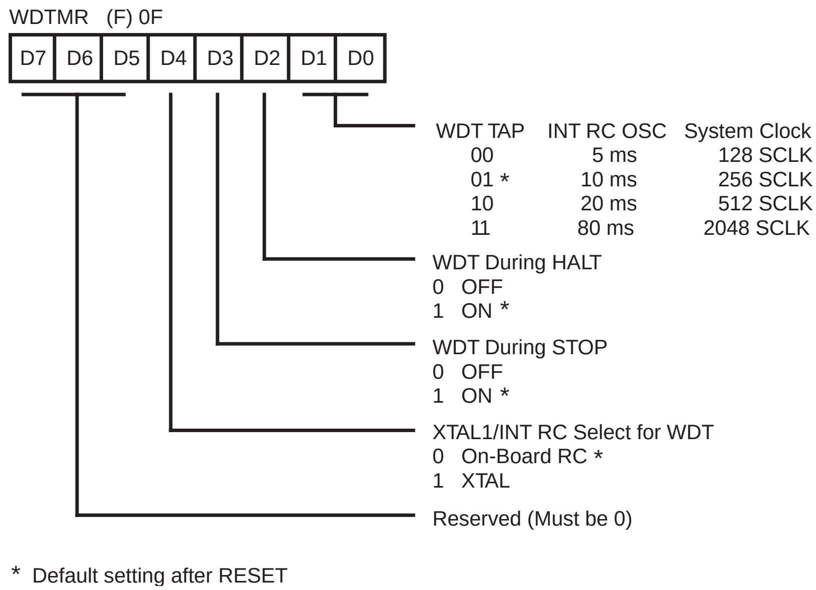


Figure 33. Watch-Dog Timer Mode Register
Write Only

Table 14. EPROM Programming Table

Programming Modes	V_{PP}	EPM	$\overline{CE}$	$\overline{OE}$	$\overline{PGM}$	ADDR	DATA	V_{CC}*
EPROM READ1	X	V_H	V_{IL}	V_{IL}	V_{IH}	ADDR	Out	4.5V†
EPROM READ2	X	V_H	V_{IL}	V_{IL}	V_{IH}	ADDR	Out	5.5V†
PROGRAM	V_H	V_H	V_{IL}	V_{IH}	V_{IL}	ADDR	In	6.4V
PROGRAM VERIFY	V_H	V_H	V_{IL}	V_{IL}	V_{IH}	ADDR	Out	6.0V
OPTION BIT PGM	V_H	V_H	V_{IL}	V_{IH}	V_{IL}	63	IN	6.4V
OPTION BIT READ	X	V_H	V_{IL}	V_{IL}	V_{IH}	63	OUT	6.0V

Notes:
V_H = 13.0 V ± 0.1 V
V_{IH} = As per specific Z8 DC specification
VIL= As per specific Z8 DC specification
X=Not used, but must be set to V_H, V_{IH}, or V_{IL} level.
NU = Not used, but must be set to either V_{IH} or V_{IL} level.
I_{PP} during programming = 40 mA maximum.
I_{CC} during programming, verify, or read = 40 mA maximum.
*V_{CC} has a tolerance of ±0.25V.
† Zilog recommends an EPROM read at V_{CC} = 4.5 V and 5.5 V to ensure proper device operations during the V_{CC} after programming, but V_{CC} = 5.0 V is acceptable.

Table 15. EPROM Programming Timing

Parameters	Name	Min	Max	Units
1	Address Setup Time	2		µs
2	Data Setup Time	2		µs
3	V_{PP} Setup	2		µs
4	V_{CC} Setup Time	2		µs
5	Chip Enable Setup Time	2		µs
6	Program Pulse Width	0.95	1.05	ms
7	Data Hold Time	2		µs
8	$\overline{OE}$ Setup Time	2		µs
9	Data Access Time	200		ns
10	Data Output Float Time		100	ns
11	Overprogram Pulse Width/Option Program Pulse Width	2.85		ms
12	EPM Setup Time	2		µs
13	$\overline{PGM}$ Setup Time	2		µs
14	Address to $\overline{OE}$ Setup Time	2		µs
15	$\overline{OE}$ Width	250		ns
16	Address to $\overline{OE}$ Low	125		ns

Z86E40 TIMING DIAGRAMS (Continued)

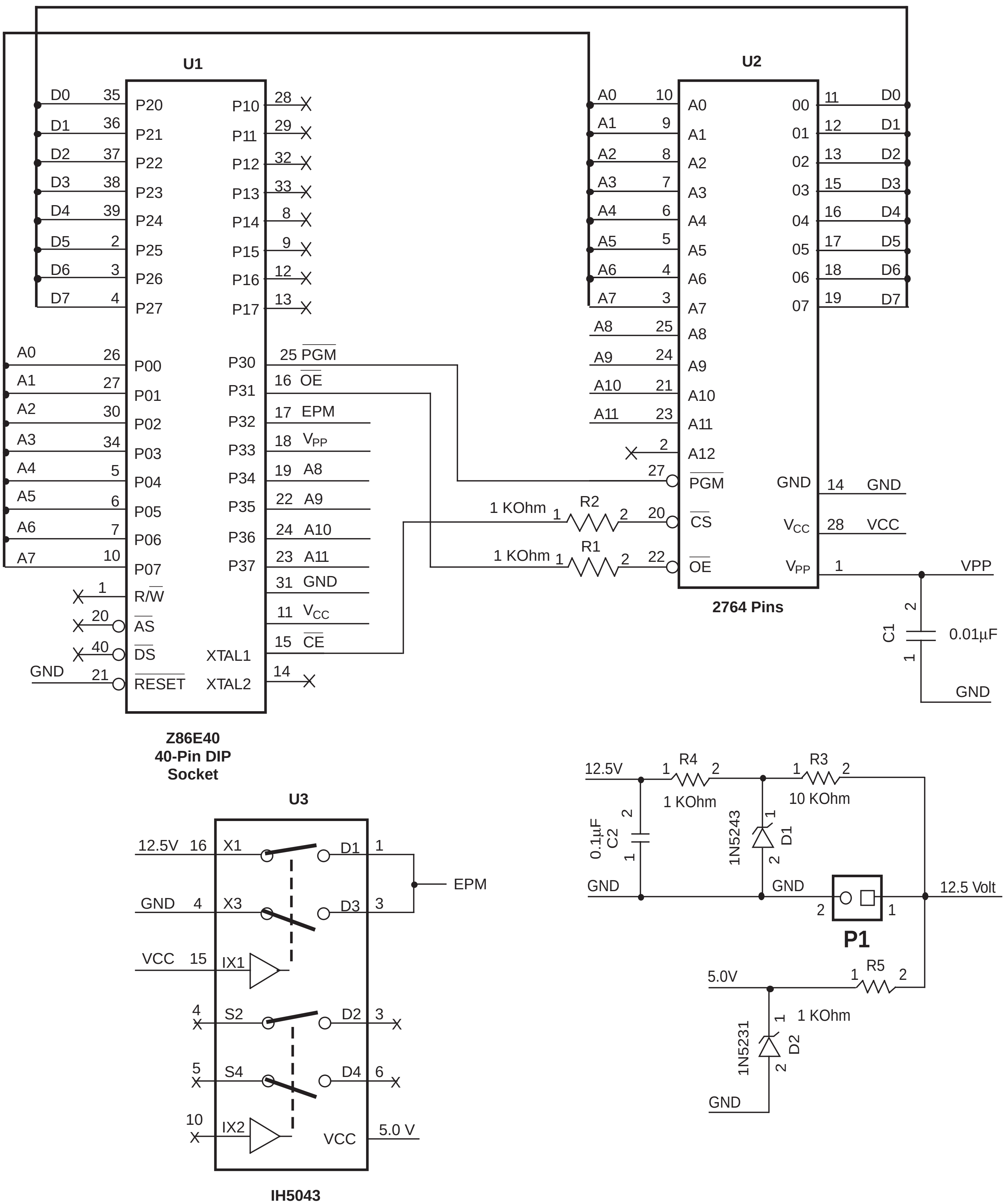
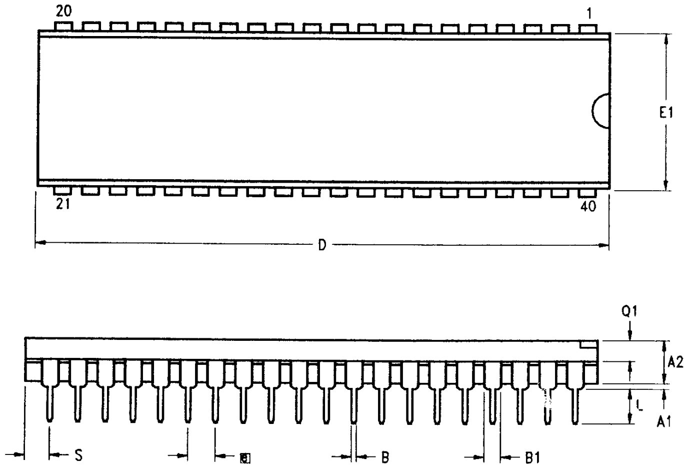


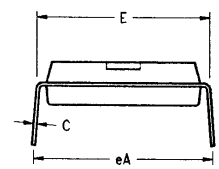
Figure 38. Z86E40 Z8 OTP Programming Adapter For use with Standard EPROM Programmers

PACKAGE INFORMATION (Continued)

PACKAGE INFORMATION

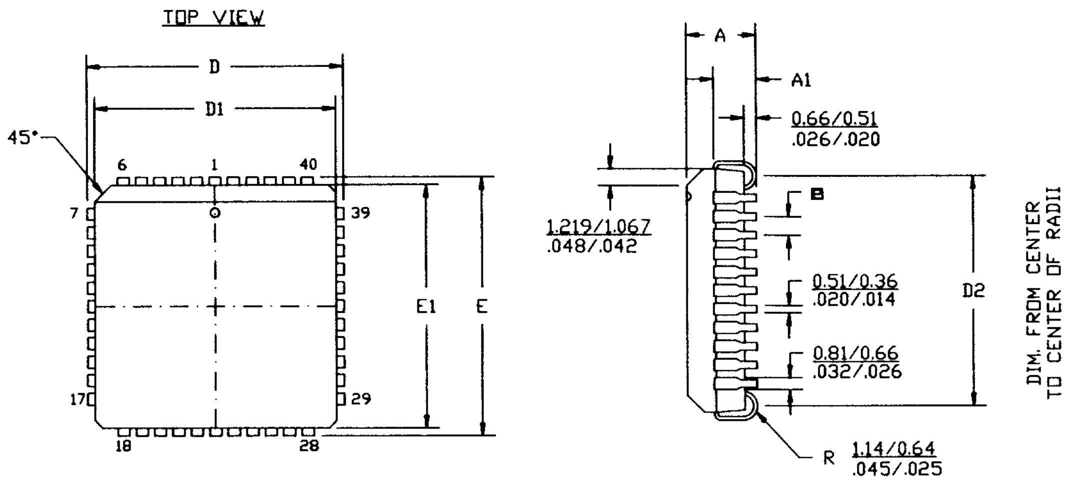


SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	1.02	.020	.040
A2	3.18	3.94	.125	.155
B	0.38	0.53	.015	.021
B1	1.02	1.52	.040	.060
C	0.23	0.38	.009	.015
D	52.07	52.58	2.050	2.070
E	15.24	15.75	.600	.620
E1	13.59	14.22	.535	.560
e	2.54 TYP		.100 TYP	
eA	15.49	16.76	.610	.660
L	3.05	3.81	.120	.150
Q1	1.52	1.91	.060	.075
S	1.52	2.29	.060	.090



CONTROLLING DIMENSIONS : INCH

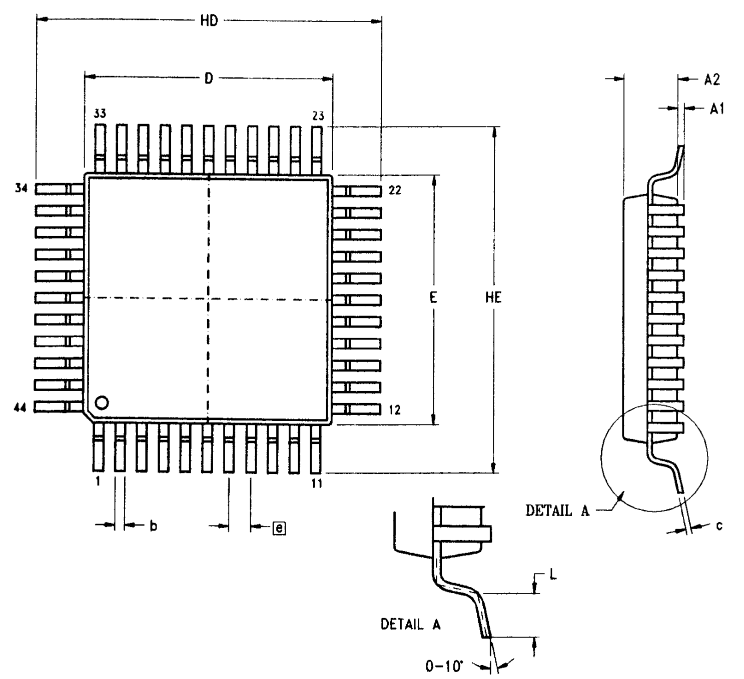
Figure 61. 40-Pin DIP Package Diagram



NOTES:
1. CONTROLLING DIMENSIONS : INCH
2. LEADS ARE COPLANAR WITHIN .004 IN.
3. DIMENSION : MM / INCH

SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	4.27	4.57	.168	.180
A1	2.41	2.92	.095	.115
D/E	17.40	17.65	.685	.695
D1/E1	16.51	16.66	.650	.656
D2	15.24	16.00	.600	.630
e	1.27 TYP		.050 TYP	

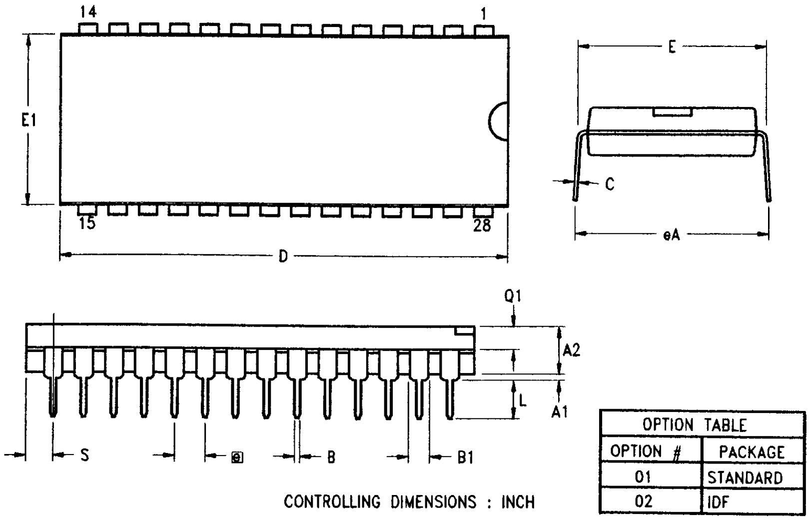
Figure 62. 44-Pin PLCC Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.05	0.25	.002	.010
A2	2.00	2.25	.078	.089
b	0.25	0.45	.010	.018
c	0.13	0.20	.005	.008
HD	13.70	14.15	.539	.557
D	9.90	10.10	.390	.398
HE	13.70	14.15	.539	.557
E	9.90	10.10	.390	.398
e	0.80 TYP		.0315 TYP	
L	0.60	1.20	.024	.047

NOTES:
1. CONTROLLING DIMENSIONS : MILLIMETER
2. LEAD COPLANARITY : MAX .10 / .004"

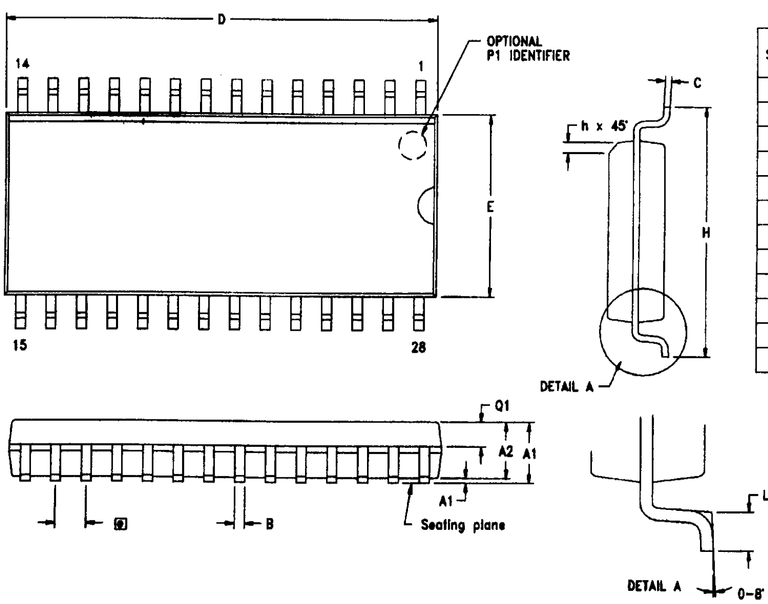
Figure 63. 44-Pin LQFP Package Diagram



OPTION TABLE	
OPTION #	PACKAGE
01	STANDARD
02	IDF

SYMBOL	OPT #	MILLIMETER		INCH	
		MIN	MAX	MIN	MAX
A1		0.51	1.02	.020	.040
A2		3.18	3.94	.125	.155
B		0.38	0.53	.015	.021
B1	01	1.40	1.65	.055	.065
	02	1.14	1.40	.045	.055
C		0.23	0.38	.009	.015
D	01	36.58	37.34	1.440	1.470
	02	35.31	35.94	1.390	1.415
E		15.24	15.75	.600	.620
E1	01	13.59	14.10	.535	.555
	02	12.83	13.08	.505	.515
e		2.54 TYP		.100 TYP	
eA		15.49	16.76	.610	.660
L		3.05	3.81	.120	.150
Q1	01	1.52	1.91	.060	.075
	02	1.52	1.78	.060	.070
S	01	1.52	2.29	.060	.090
	02	1.02	1.52	.040	.060

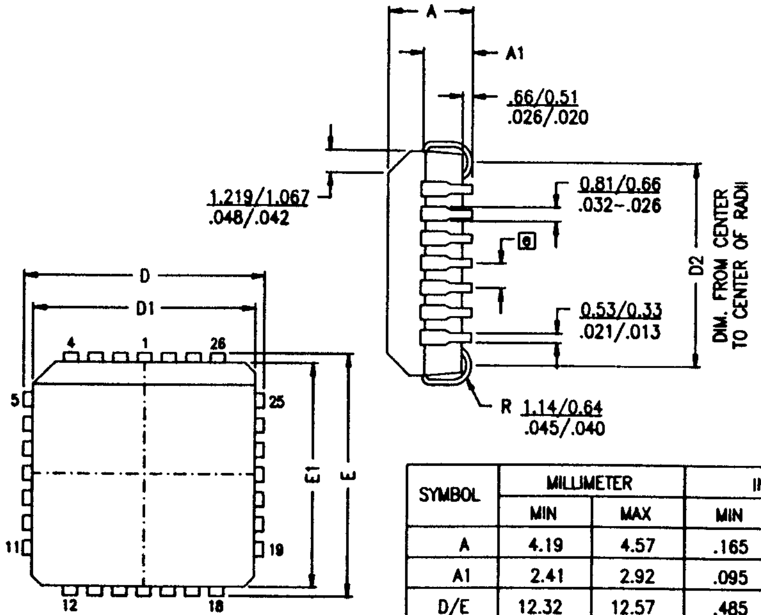
Figure 64. 28-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.64	.094	.104
A1	0.10	0.30	.004	.012
A2	2.24	2.44	.088	.096
B	0.36	0.46	.014	.018
C	0.23	0.30	.009	.012
D	17.78	18.00	.700	.710
E	7.40	7.60	.291	.299
e	1.27 typ		.050 typ	
H	10.00	10.65	.394	.419
h	0.30	0.71	.012	.028
L	0.61	1.00	.024	.039
Q1	0.97	1.07	.038	.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 65. 28-Pin SOIC Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	4.19	4.57	.165	.180
A1	2.41	2.92	.095	.115
D/E	12.32	12.57	.485	.495
D1/E1	11.43	11.58	.450	.456
D2	9.91	10.92	.390	.430
e	1.27 TYP		.050 TYP	

NOTES.
1. CONTROLLING DIMENSIONS : INCH
2. LEADS ARE COPLANAR WITHIN .004 INCH.
3. DIMENSION : MM / INCH

Figure 66. 28-Pin PLCC Package Diagram

ORDERING INFORMATION

Z86E40 (16 MHz)

40-Pin DIP	44-Pin PLCC	44-Pin LQFP
Z86E4016PSC	Z86E4016VSC	Z86E4016FSC
Z86E4016PEC	Z86E4016VEC	Z86E4016FEC

Z86E30 (16 MHz)

28-Pin DIP	28-Pin SOIC	28-Pin PLCC
Z86E3016PSC	Z86E3016SSC	Z86E3016VSC
Z96E3016PEC	Z86E3016SEC	Z86E3016VEC

Z86E31 (16 MHz)

28-Pin DIP	28-Pin SOIC	28-Pin PLCC
Z86E3116PSC	Z86E3116SSC	Z86E3116VSC
Z86E3116PEC	Z86E3116SEC	Z86E3116VEC

For fast results, contact your local Zilog sales office for assistance in ordering the part desired.

Package

P = Plastic DIP

V = Plastic Leaded Chip Carrier

F = Plastic Quad Flat Pack

S = SOIC (Small Outline Integrated Circuit)

Temperature

S = 0 °C to +70 °C
E = -40 °C to +105 °C

Speed

16 = 16 MHz

Environmental

C= Plastic Standard

E = Hermetic Standard

Example:

Z 86E40 16 P S C is a Z86E40, 16 MHz, DIP, 0°C to +70°C, Plastic Standard Flow

- C — Environmental Flow
- S — Temperature
- P — Package
- 16 — Speed
- 86E40 — Product Number
- Z — Zilog Prefix